



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

July 15, 2004

Applicant(s): Uwe HOFMANN et al.

For: LEAD-FREE COPPER ALLOY AND A METHOD OF MANUFACTURE

Serial No.: 10/786 470 Group: 1742

Confirmation No.: 9330

Filed: February 25, 2004 Examiner: Unknown

Atty. Docket No.: W-Werke 62

Mail Stop Missing Parts
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

In compliance with the provisions of Rules 1.97(b)(3) and 1.98, enclosed herewith is Form PTO-1449 and one copy of the Patent Abstracts of Japan for Publication No. JP 55008375.

More specifically, DE 43 08 371 C2 and DE 691 24 835 T2 are mentioned in Applicants' specification. The two German references have corresponding U.S. patents, namely, 5 346 668 and 5 167 726, respectively. Therefore, the two U.S. patents have been listed on the enclosed Form PTO-1449. Since this application was filed after June 30, 2003, Applicants hereby accept the USPTO waiver of the requirement under 37 CFR 1.98(a)(2)(i) for submitting a copy of each cited U.S. patent [1273 Off. Gaz. Pat. Off. 55, 8/05/2003].

The enclosed Patent Abstracts of Japan for Publication No. JP 55008375 constitutes the additional art known to the Applicants and is believed to be distinguishable from the claimed invention. Accordingly, further comment at this point in time should not be necessary.

Further consideration is respectfully solicited.

Respectfully submitted,



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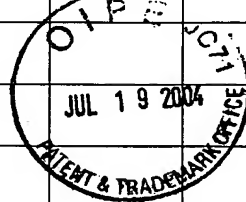
Encl: Form PTO-1449
Patent Abstracts of Japan for
Japanese Publication No. 55008375 A (1 page)

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	Group : 1742

U.S. PATENT DOCUMENTS

Examiner Initial*	Document Number	Date	Name	Class	Sub Class	Filing Date
AA	5 167 726	12/01/1992	LoIacono et al.			
AB	5 346 668	09/13/1994	Tanaka et al.			
AC						
AD						
AE						
AF						
AG						
AH						
AI						
AJ						
AK						



FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Sub Class	Translation Yes No
AL						
AM						
AN						
AO						
AP						

OTHER DOCUMENTS (Including Author, Title, Date, Pages, Etc.)

AR	PATENT ABSTRACTS OF JAPAN for JP Publication No. 55008375 A, published January 21, 1980 (1 page)
AS	

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.